Abstract

A temporary package for a semiconductor die is provided. The temporary package has an outline and external contact configuration that are the same as a conventional plastic or ceramic semiconductor package. The temporary package can be used for burn-in testing of the die using standard equipment. The die can then be removed from the package and certified as a known good die. The package includes a base, an interconnect and a force applying mechanism. The package base includes external contacts formed in a dense array, such as a land grid array (LGA), a pin grid array (PGA), a bumped grid array (BGA) or a perimeter array. The package base can be formed of ceramic or plastic with internal conductive lines using a ceramic lamination process, a 3-D molding process or a Cerdip formation process.

Figure 1

THIS SHEET HAS BEEN REPLACED

This Sheet Has Been Replaced

